



HPH2369

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HPH2369 is designed for general purpose switching and amplifier applications.

Features

- Low Collector Saturation
- Voltage High speed switching Transistor

Absolute Maximum Ratings

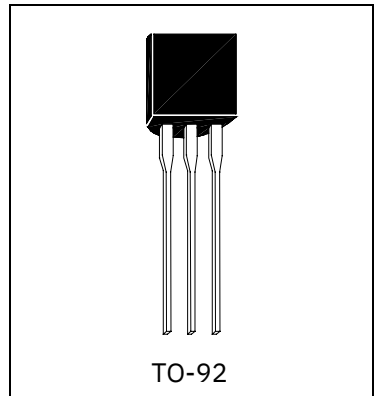
- Maximum Temperatures
 Storage Temperature..... -55 ~ +150 °C
 Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C)..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage..... 40 V
 VCES Collector to Emitter Voltage..... 40 V
 VCEO Collector to Emitter Voltage..... 15 V
 VEBO Emitter to Base Voltage..... 4.5 V
 IC Collector Current 500 mA

(Ta=25°C)

Characteristics

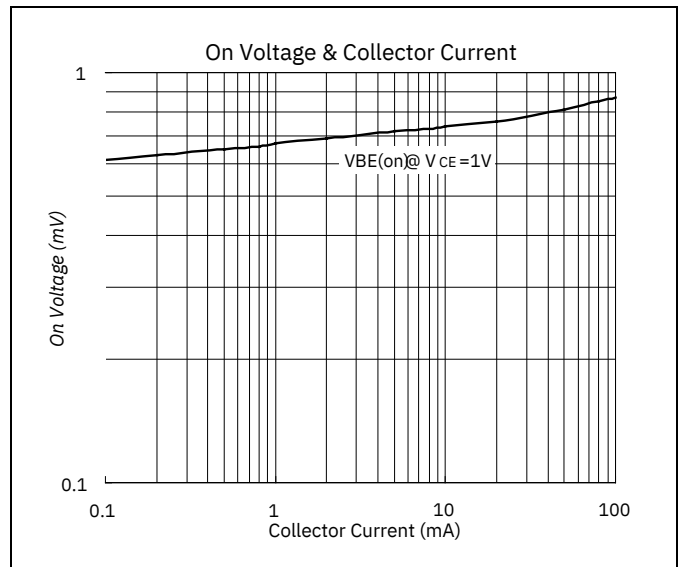
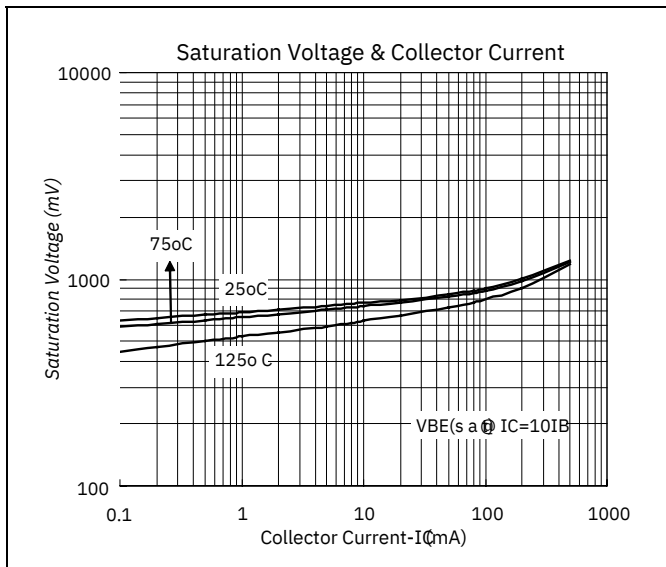
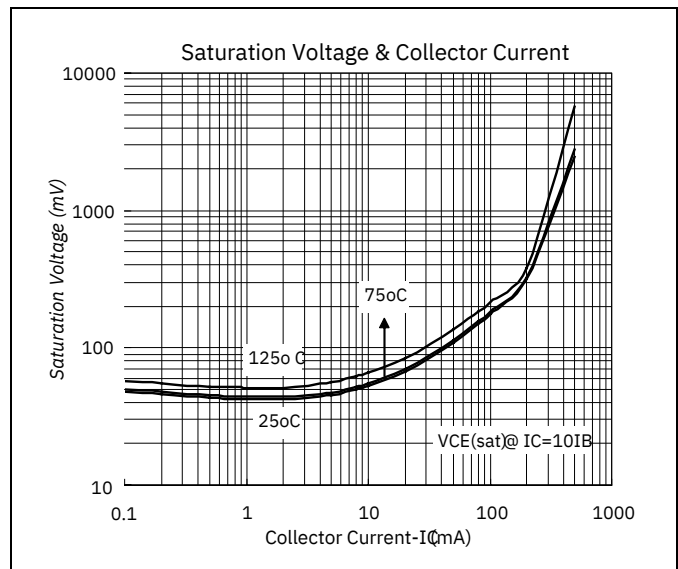
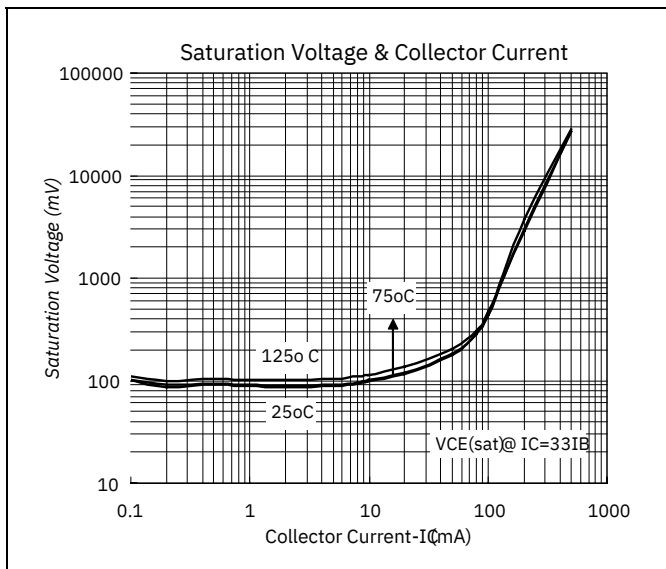
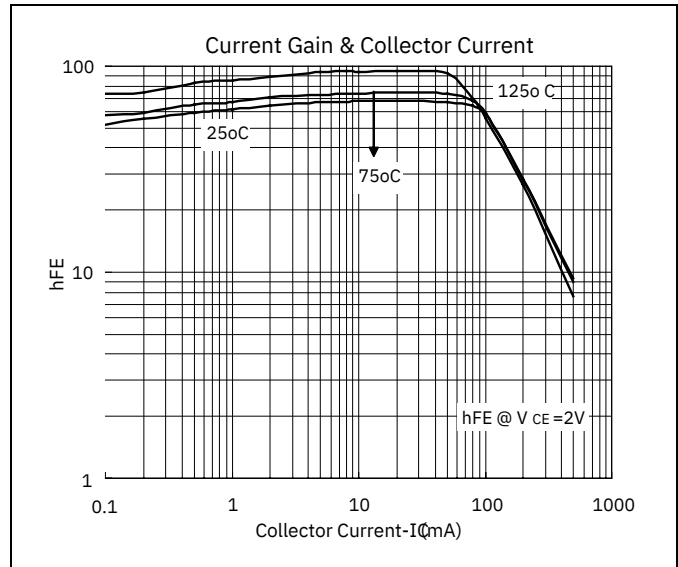
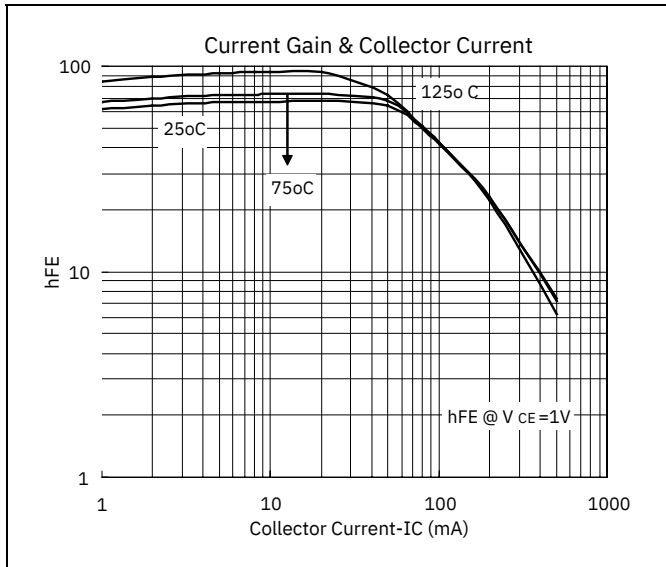
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	--	VIC=100μA, IE=0		
BVCEO	15	--	VIC=10mA, IB=0		
BVCE	40	--	VIC=10μA, VBE=0		
BVEBO	4.5	--	VIE=10μA, IC=0		
ICBO	--	400nA	VCB=20V, IE=0		
ICES	--	300nA	VCE=25V, VBE=0		
IEBO	--	100nA	VEB=2V, IC=0		
*VCE(sat)1	--	250mV	VIC=10mA, IB=1mA		
*VCE(sat)2	--	300mV	VIC=10mA, IB=0.3mA		
*VCE(sat)3	--	600mV	VIC=100mA, IB=10mA		
*VBE(sat)1	700	--	850mV	VIC=10mA, IB=1mA	
*VBE(sat)2	--	1.5V	VIC=100mA, IB=1mA		
*hFE140	80	120	IC=10mA, VCE=1V		
*hFE220	--	IC=100mA, VCE=2V			
			fT500--MHz	IC=10mA, VCE=10V, f=100MHZ	
Cob	--	4pF	VCB=5V, f=1MHz, IE=0		
≤	≤				

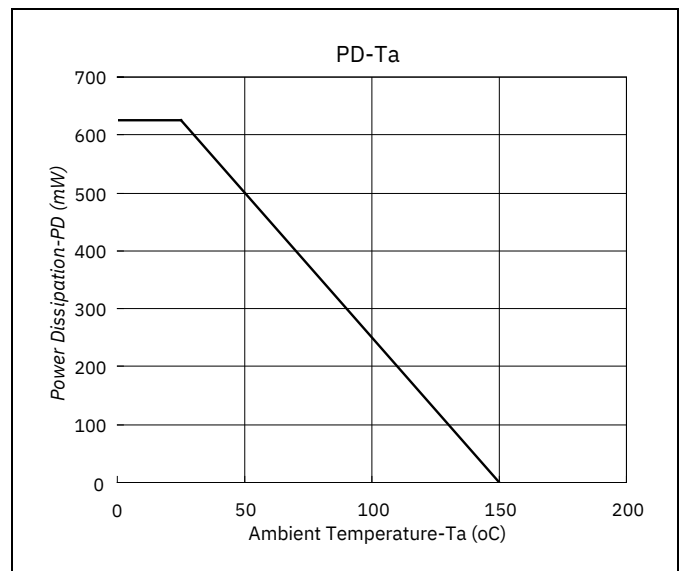
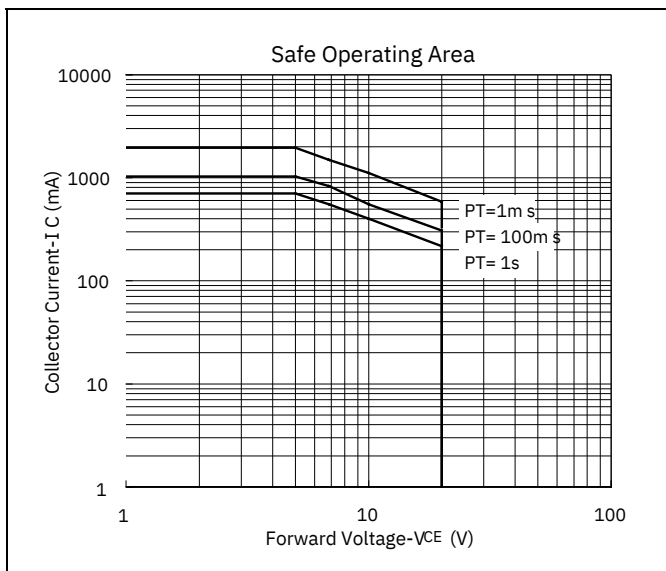
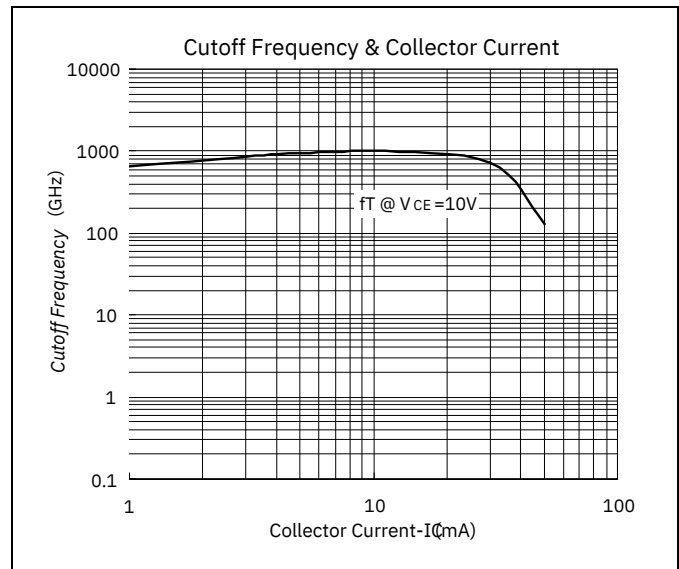
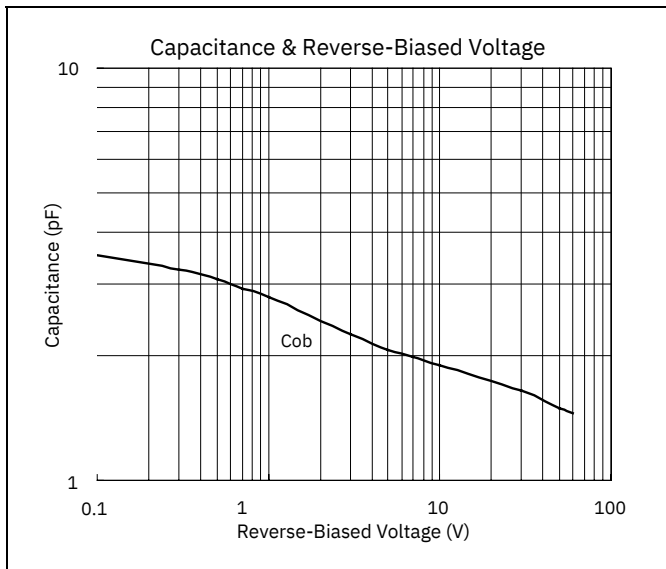
*Pulse Test: Pulse Width 380us, Duty Cycle 2%





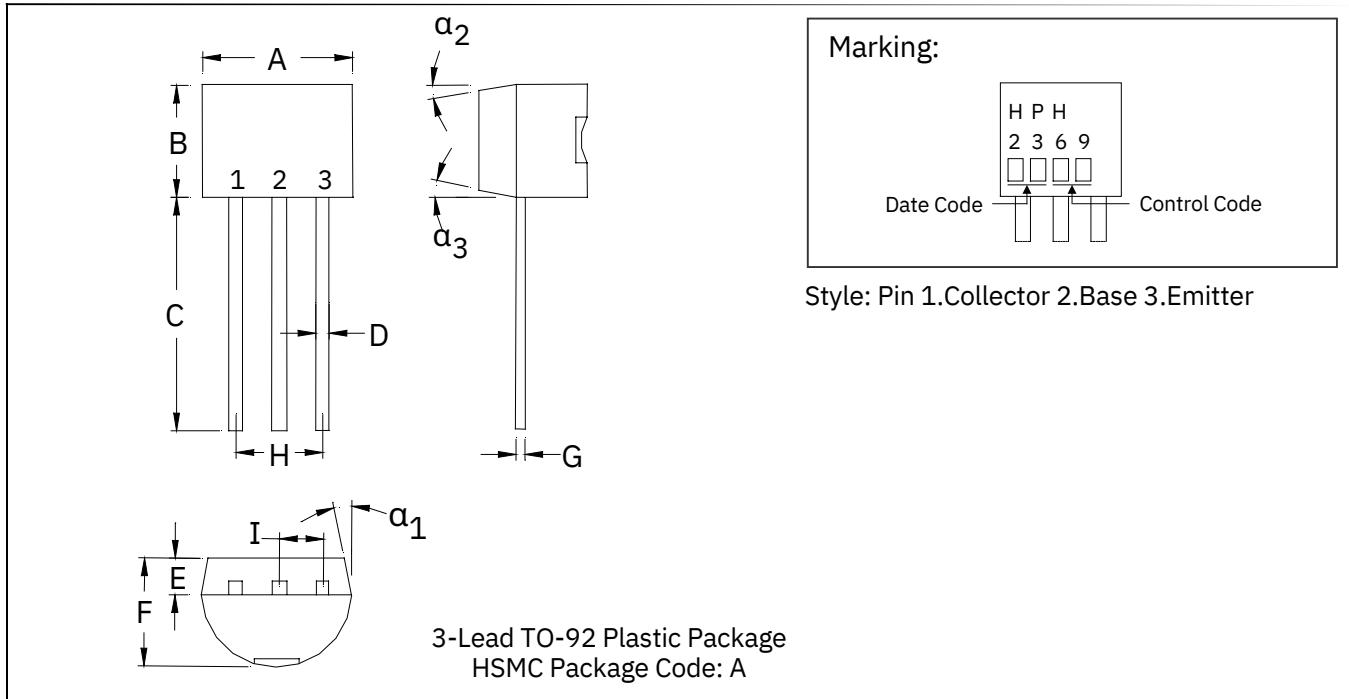
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5	-	*5
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2	-	*2
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2	-	*2

- Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- * Lead: 42 Alloy; solder plating
- * Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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